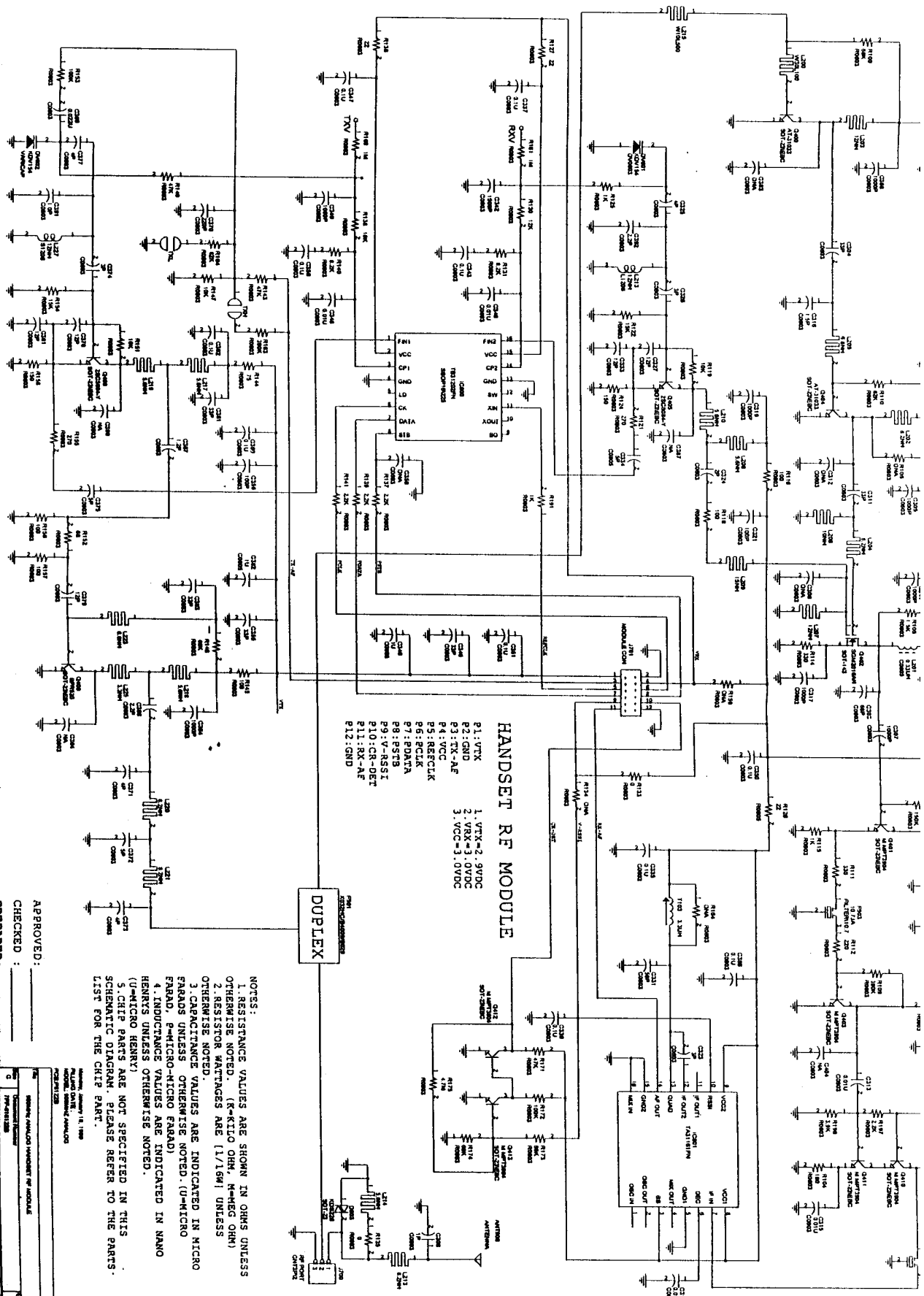




HANDSET RF MODULE

1. VTX=2.9VDC
 2. VTX=3.0VDC
 3. VCC=3.0VDC

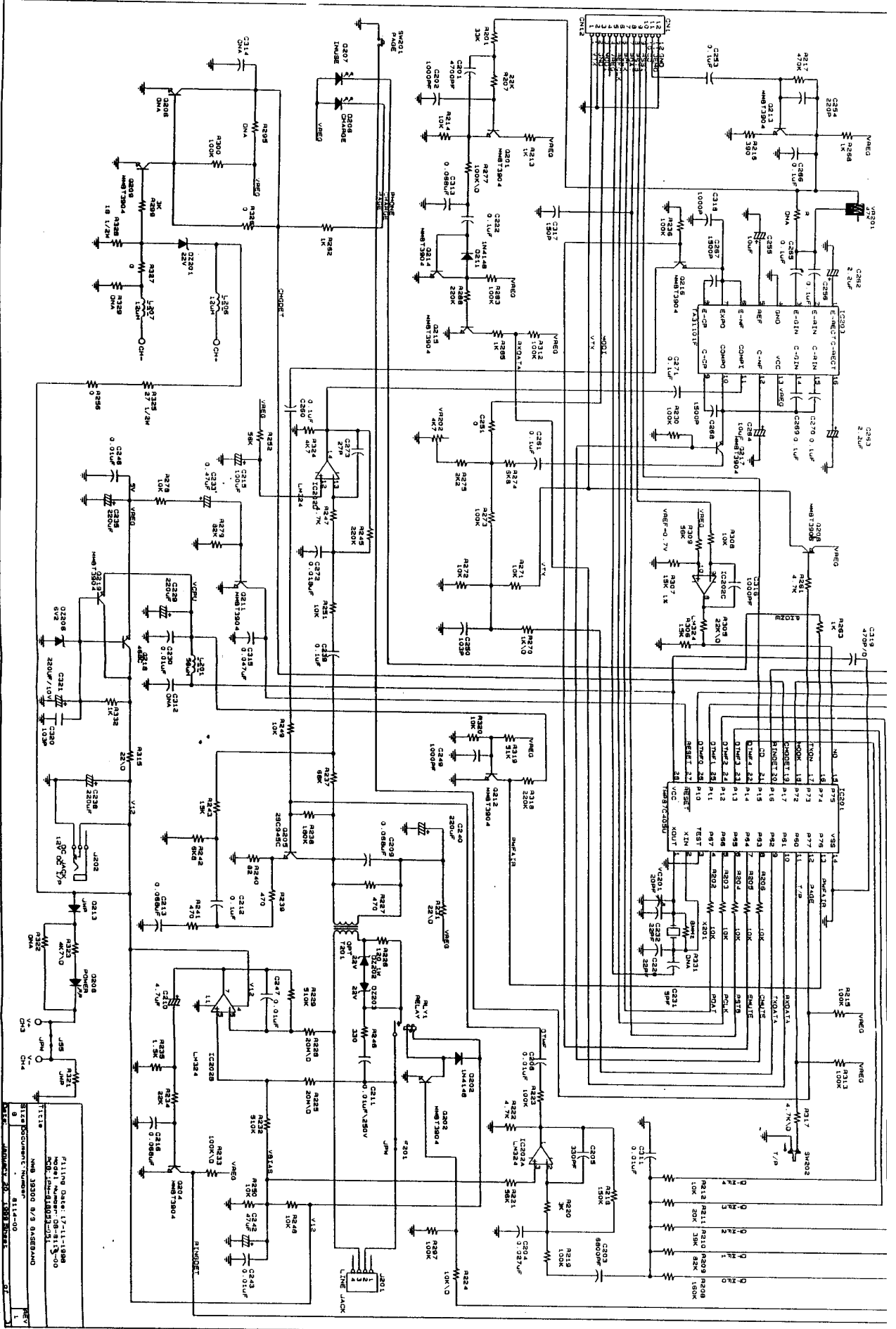
DUPLEX

NOTES:

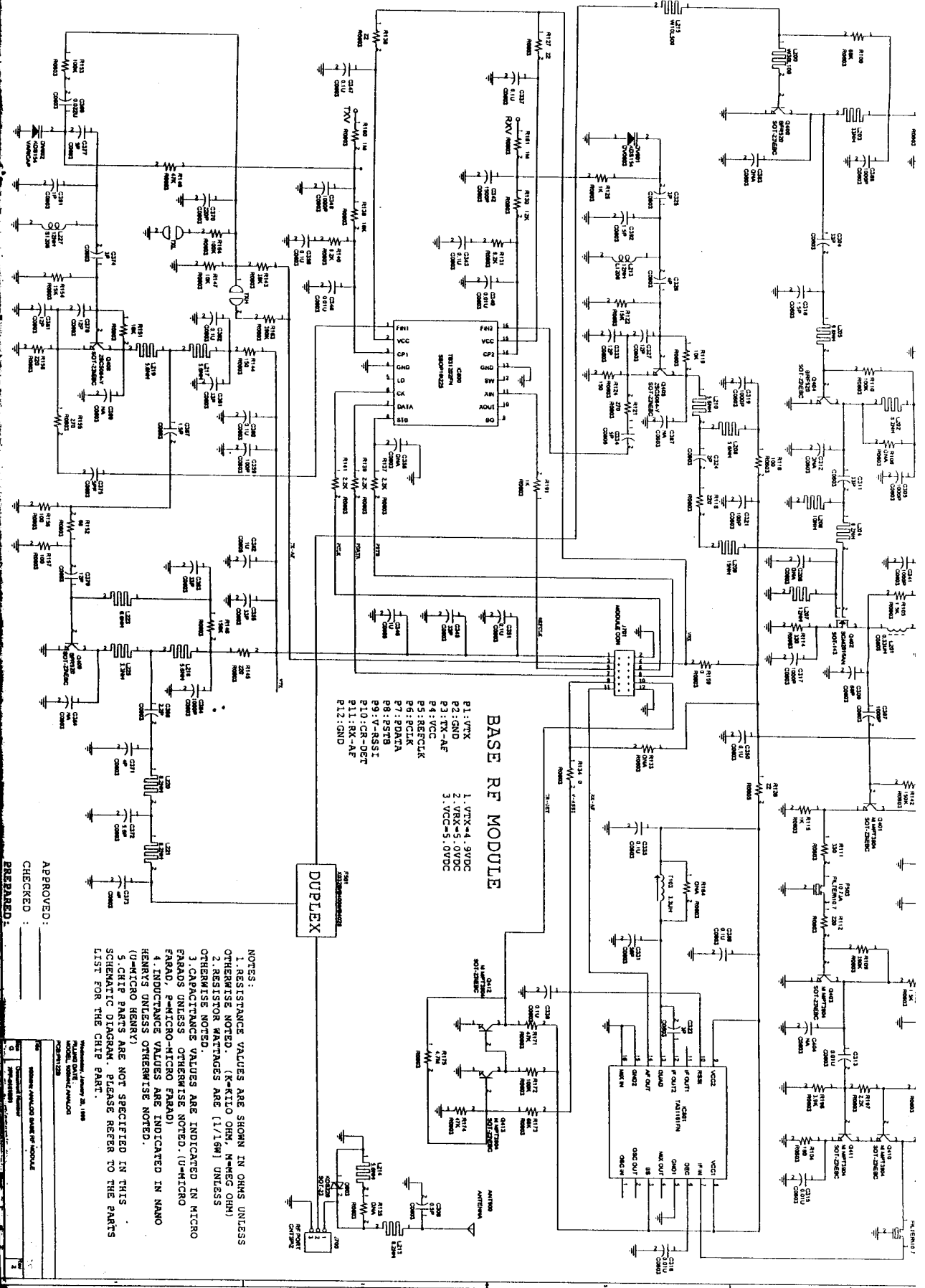
1. RESISTANCE VALUES ARE SHOWN IN OHMS UNLESS OTHERWISE NOTED. (R-KILO OHM, M-MEG OHM)
2. RESISTOR WATTAGES ARE [1/16W] UNLESS OTHERWISE NOTED.
3. CAPACITANCE VALUES ARE INDICATED IN MICRO FARADS UNLESS OTHERWISE NOTED. (U-MICRO FARAD, P-MICRO-MICRO FARAD)
4. INDUCTANCE VALUES ARE INDICATED IN NAHO HENRYS UNLESS OTHERWISE NOTED.
5. CHIP PARTS ARE NOT SPECIFIED IN THIS SCHEMATIC DIAGRAM. PLEASE REFER TO THE PARTS LIST FOR THE CHIP PART.

APPROVED: _____
 CHECKED: _____

NO.	REVISION	DATE	BY	DESCRIPTION
1	1	10/1/80	W. J. BROWN	INITIAL RELEASE
2	2	10/1/80	W. J. BROWN	INITIAL RELEASE



File Name: 17-11-1988
Model Number: 08-8113-00
Rev: 001
Date: 17-11-1988
Drawing Number: 8114-00
Sheet: 01 of 01



BASE RF MODULE

- 1. VTX=4.9VDC
- 2. VTX=5.0VDC
- 3. VCC=5.0VDC

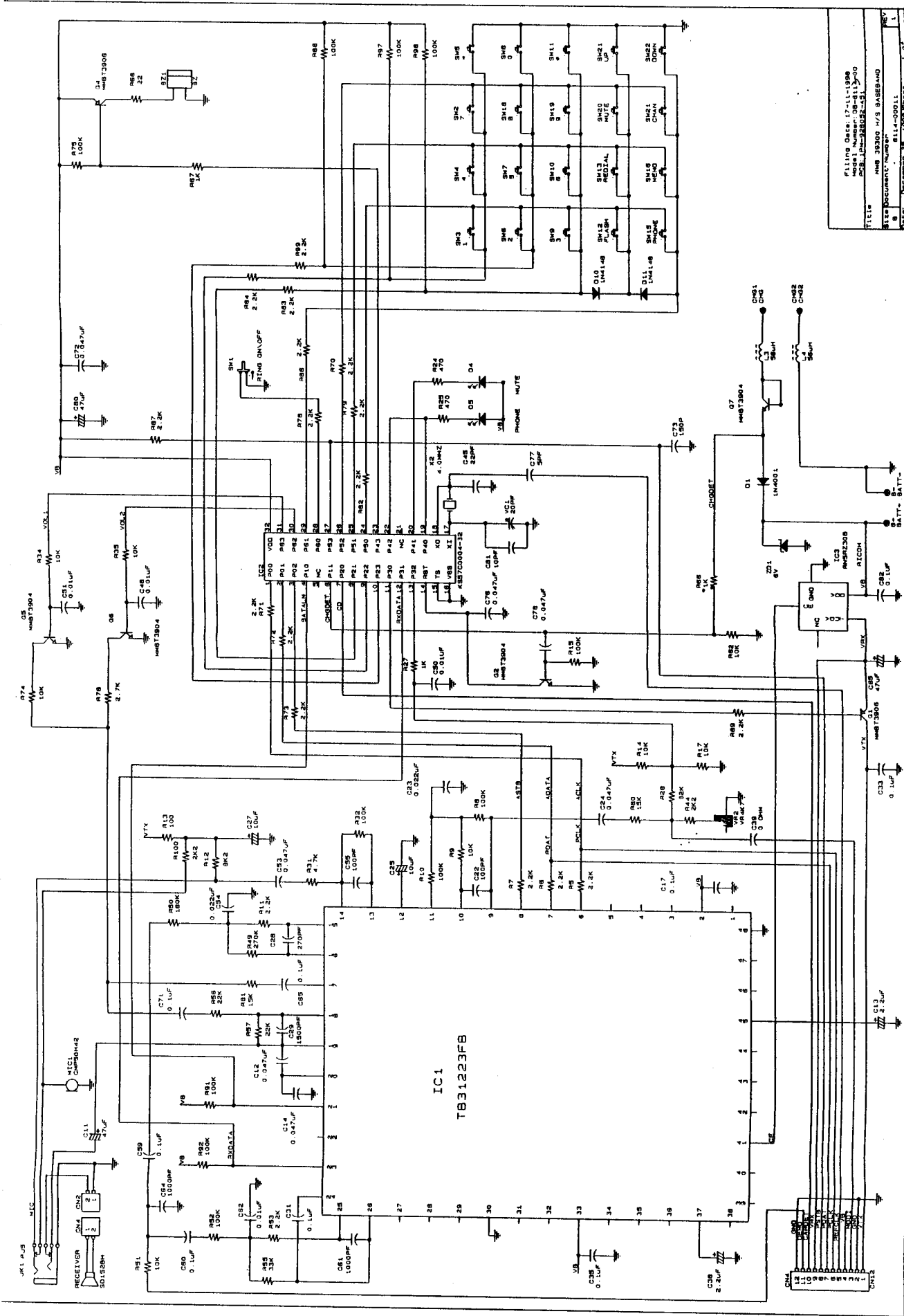
DUPLEX

NOTES:

1. RESISTANCE VALUES ARE SHOWN IN OHMS UNLESS OTHERWISE NOTED. (K=KILO OHM, M=MEG OHM)
2. RESISTOR WATTAGES ARE (1/16W) UNLESS OTHERWISE NOTED.
3. CAPACITANCE VALUES ARE INDICATED IN MICRO FARAD, P=PICO-MICRO FARAD
4. INDUCTANCE VALUES ARE INDICATED IN NANO HENRY UNLESS OTHERWISE NOTED.
5. CHIP PARTS ARE NOT SPECIFIED IN THIS SCHEMATIC DIAGRAM. PLEASE REFER TO THE PARTS LIST FOR THE CHIP PART.

APPROVED: _____
 CHECKED: _____
 PREPARED: _____

DATE	REVISION
10/10/00	1
REVISIONS	
NO	REVISIONS
1	REVISIONS
2	REVISIONS
3	REVISIONS
4	REVISIONS
5	REVISIONS
6	REVISIONS
7	REVISIONS
8	REVISIONS
9	REVISIONS
10	REVISIONS



Filing Date: 17-11-1990
Model Number: DB-513-00
Circuit: DB-513-00
Title: HMB 3300 V/S BASEBAND
Sheet: 1 of 1
Drawing Number: 1-1001-1
Rev: 1